


NOTES

1. MATERIALS:
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.
2. FINISH:
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICRONS (2.5um-7.6um) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICRONS (1um-2um) THICK).
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.
5. PACKAGE CONFORMS TO JEDEC MO-220

PROPRIETARY AND CONFIDENTIAL
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		UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: ANGULAR: ±0.5 degree .X = ±0.76 .XX: ±0.25 .XXX = ±0.13 .XXXX = ±0.01		DRAWN	D. Abbe	8/15/11	 TITLE: QP-QFN24-5MM-0.65MM
				CHECKED	S. Swen	8/15/11	
				ENG APPR.	S. Swen	8/15/11	
				COMMENTS:			SIZE B DWG. NO. 500417 REV A
NEXT ASSY		USED ON		MATERIAL		SEE NOTE 1	
APPLICATION		DO NOT SCALE DRAWING		FINISH		SEE NOTE 2	
				SCALE: 10:1		WEIGHT: SHEET 1 OF 1	



QP-QFN24-5MM-0.65MM

SIZE **B** DWG. NO. **500417** REV **A**

SCALE: 10:1 WEIGHT: SHEET 1 OF 1